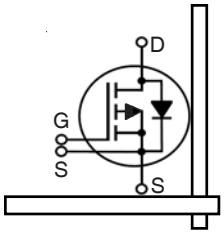
IXYS

PolarP™ Power MOSFET

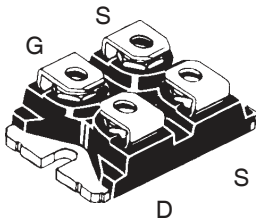
IXTN170P10P

V_{DSS} = -100V
I_{D25} = -170A
$R_{DS(on)}$ ≤ 14mΩ

P-Channel Enhancement Mode
Avalanche Rated



miniBLOC, SOT-227
E153432



G = Gate D = Drain
S = Source

Either Source Terminal at miniBLOC can be used as Main or Kelvin Source.

Symbol	Test Conditions		Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C		-100	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ		-100	V
V_{GSS}	Continuous		±20	V
V_{GSM}	Transient		±30	V
I_{D25}	T_C = 25°C		-170	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}		- 510	A
I_A	T_C = 25°C		-170	A
E_{AS}	T_C = 25°C		3.5	J
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$		10	V/ns
P_D	T_C = 25°C		890	W
T_J			-55 ... +150	°C
T_{JM}			150	°C
T_{stg}			-55 ... +150	°C
V_{ISOL}	50/60 Hz, RMS	t = 1 minute	2500	V~
	$I_{ISOL} \le$ 1mA	t = 1 second	3000	V~
M_d	Mounting Torque		1.5/13	Nm/lb.in.
	Terminal Connection Torque		1.3/11.5	Nm/lb.in.
Weight			30	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = - 250μA	-100			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = -1mA	- 2.0		- 4.0	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			- 50	μA
	T_J = 125°C			- 250	μA
$R_{DS(on)}$	V_{GS} = -10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			14	mΩ

Features

- International Standard Package
- miniBLOC, with Aluminium Nitride Isolation
- Rugged PolarP™ Process
- High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- High-Side Switches
- Push Pull Amplifiers
- DC Choppers
- Automatic Test Equipment
- Current Regulators

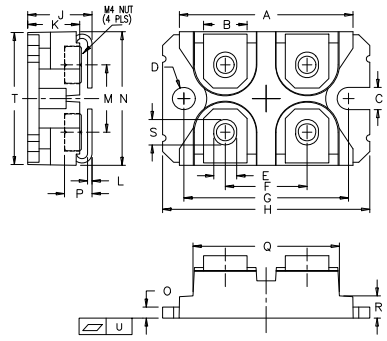
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = -10V, I_D = 0.5 • I_{D25}, Note 1	35	58		S
C_{iss}	V_{GS} = 0V, V_{DS} = - 25V, f = 1MHz		12.6		nF
C_{oss}			4190		pF
C_{rss}			930		pF
$t_{d(on)}$	**Resistive Switching Times**		32		ns
t_r	V_{GS} = -10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0 .5 • I_{D25}		75		ns
$t_{d(off)}$	R_G = 1Ω (External)		82		ns
t_f			45		ns
$Q_{g(on)}$	V_{GS} = -10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		240		nC
Q_{gs}			45		nC
Q_{gd}			120		nC
R_{thJC}				0.14	°C/W
R_{thCS}			0.05		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			-170	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			- 680	A
V_{SD}	I_F = - 85A, V_{GS} = 0V, Note 1			- 3.3	V
t_{rr}	I_F = - 85A, -di/dt = -100A/μs		176		ns
Q_{RM}	V_R = - 50V, V_{GS} = 0V		1.25		μC
I_{RM}			-14.2		A

Note 1: Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

SOT-227B (IXTN) Outline



(M4 screws (4x) supplied)

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

Fig. 1. Output Characteristics @ T_J = 25°C

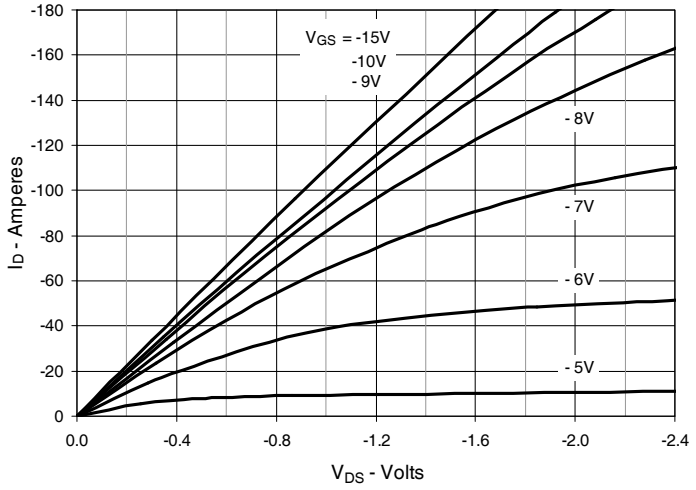


Fig. 2. Extended Output Characteristics @ T_J = 25°C

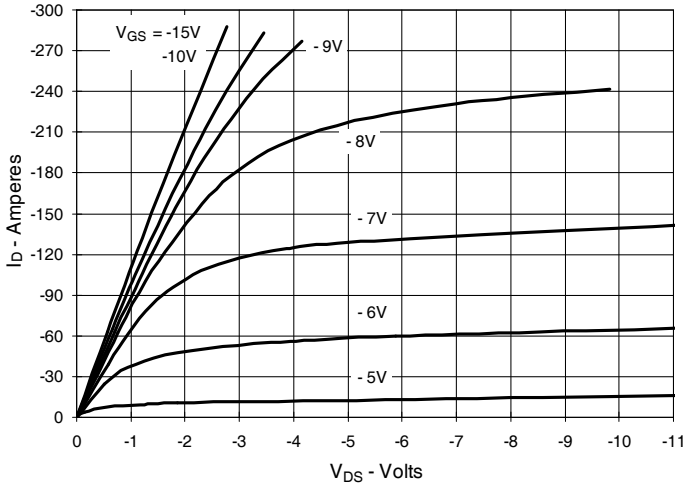


Fig. 3. Output Characteristics @ T_J = 125°C

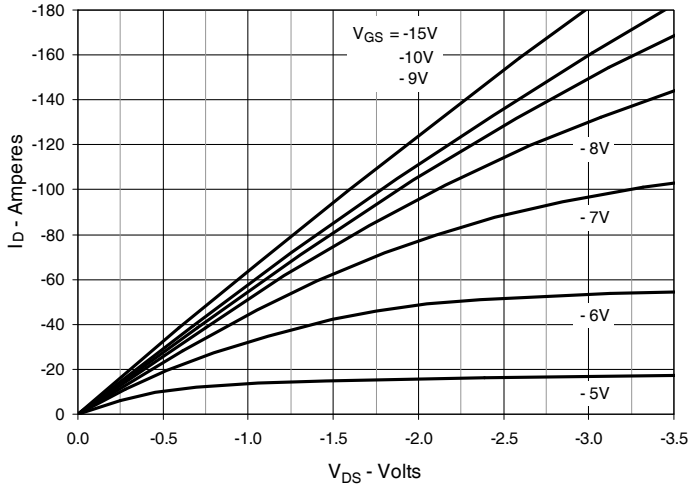


Fig. 4. $R_{DS(on)}$ Normalized to I_D = - 85A Value vs. Junction Temperature

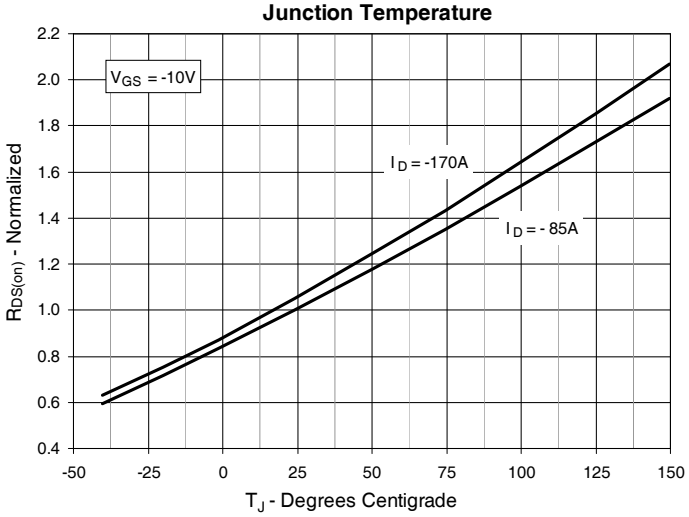


Fig. 5. $R_{DS(on)}$ Normalized to I_D = - 85A Value vs. Drain Current

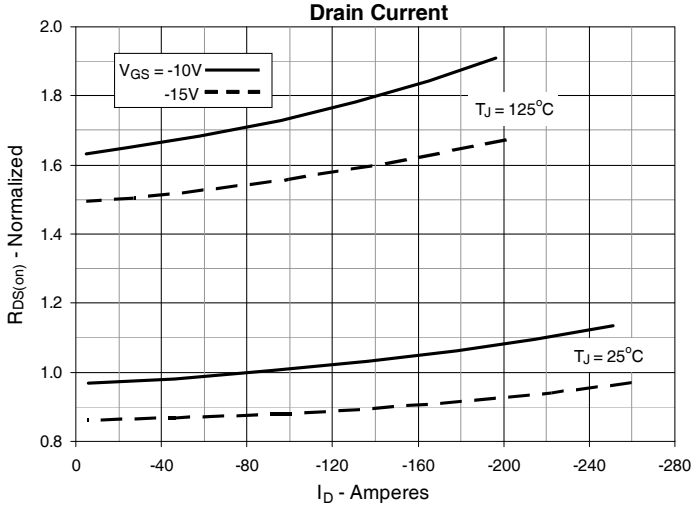


Fig. 6. Maximum Drain Current vs. Case Temperature

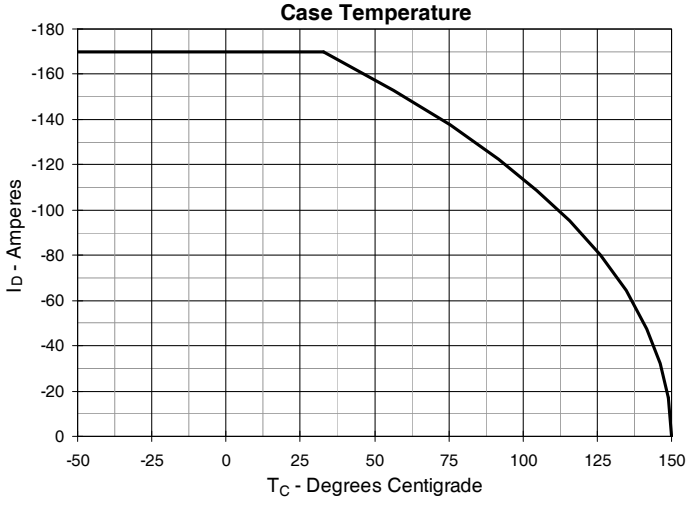


Fig. 7. Input Admittance

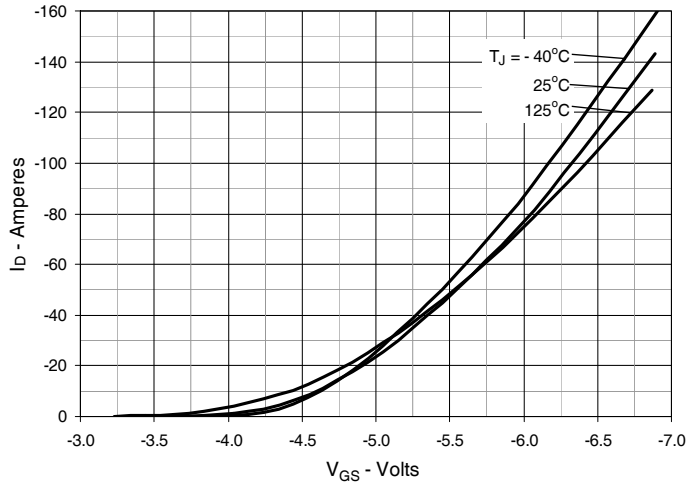


Fig. 8. Transconductance

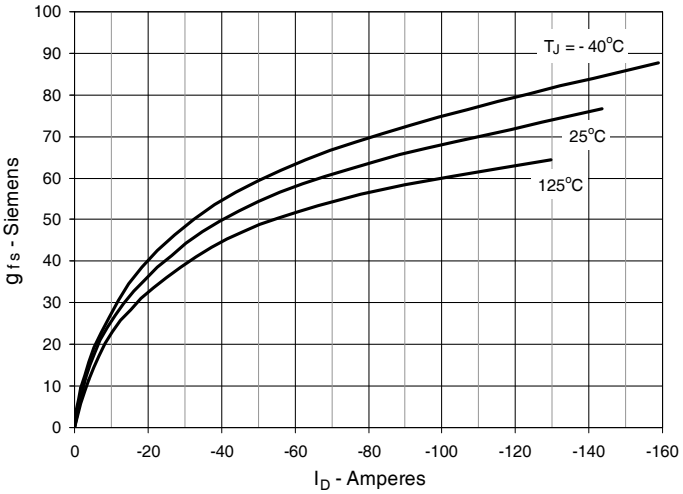


Fig. 9. Forward Voltage Drop of Intrinsic Diode

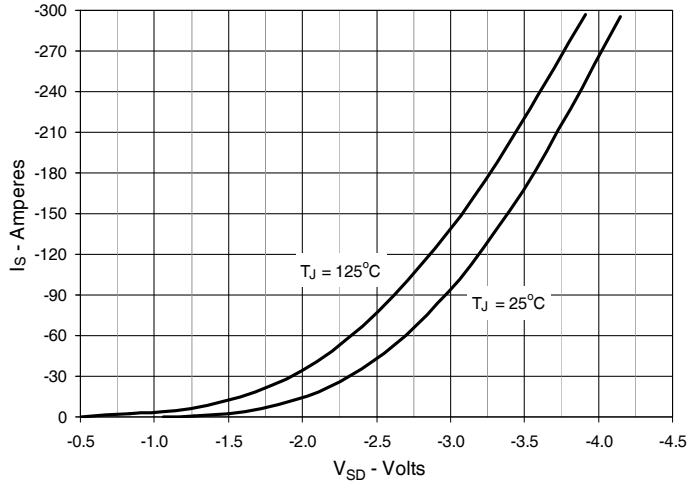


Fig. 10. Gate Charge

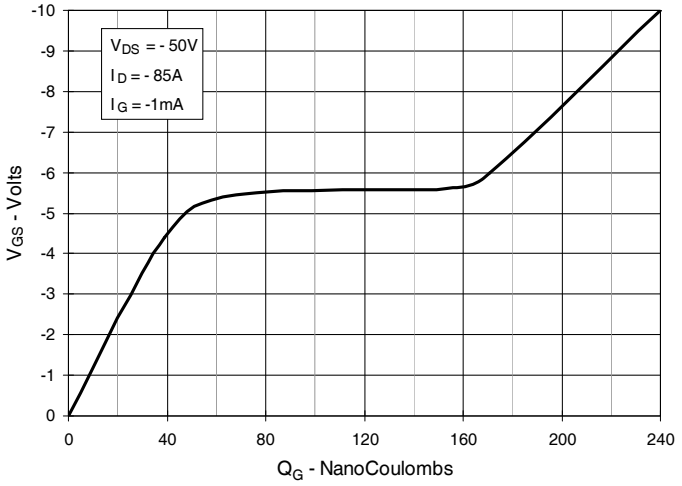


Fig. 11. Capacitance

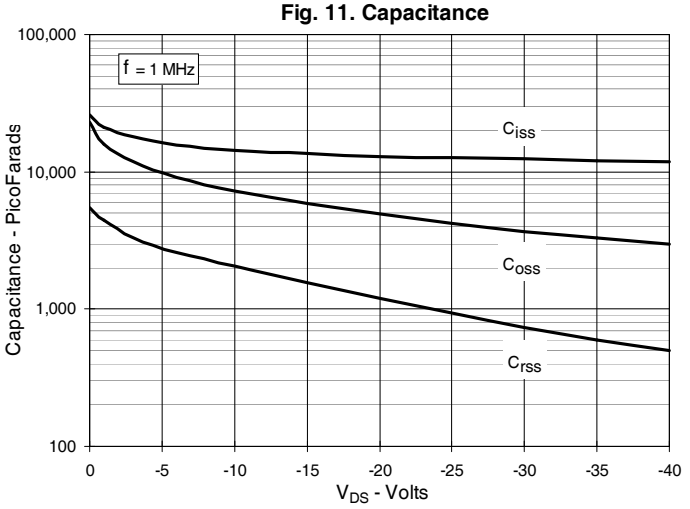


Fig. 12. Forward-Bias Safe Operating Area

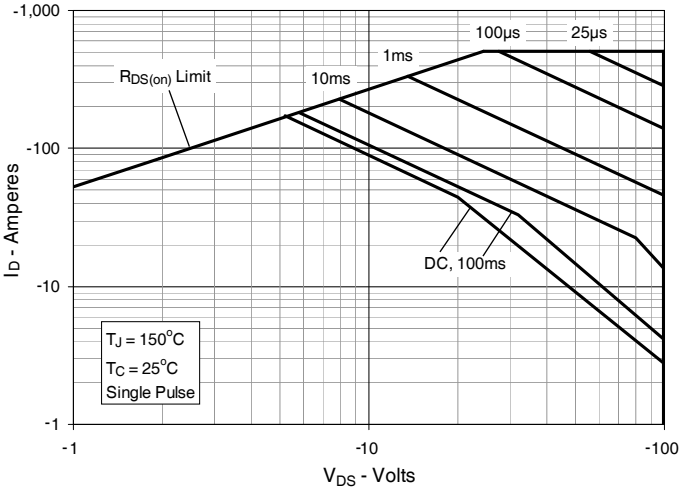


Fig. 13. Maximum Transient Thermal Impedance